

### **General Description**

The MAX1698 and MAX1698A are efficient drivers for white or color LEDs. They are ideal for large LED backlit displays in PDAs and laptop computers. Numerous benefits include greater simplicity, lower cost, higher efficiency, longer bulb life, and greater reliability when compared to fluorescent (CCFL) and electroluminescent (EL) lamps.

The MAX1698/MAX1698A are switch-mode boost controllers in which LED current, rather than output voltage, is regulated The devices drive series-connected LEDs with a controlled current that is measured with a typically 15 $\Omega$  sense resistor, not an expensive fractional-ohm value. LED current control and dimming are accomplished with an adjust input (ADJ). For larger light output, multiple LED banks can be connected in parallel with up to 5W total output power.

The MAX1698A has a higher, and more accurately specified, CS current limit than the MAX1698 for higherpower applications of 5W or more. Both devices are supplied in a space-saving 10-pin µMAX package that occupies half the space of an 8-pin SO. An evaluation kit (MAX1698EVKIT) is available to speed designs.

## **Applications**

Battery-Powered Backlight Applications Backlight for LCD Panels Notebook PCs Handy Terminals **PDAs** 

## ♦ Over 90% Efficiency

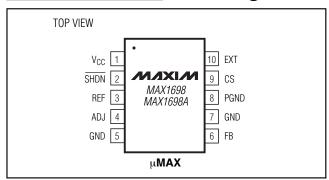
- ♦ Lossless, Adjustable LED Brightness
- ♦ Space-Saving 10-Pin µMAX Package
- ♦ Simpler, Lower Cost, More Reliable Compared to CCFL or EL Backlights
- ♦ Up to 5W Output Power

### **Ordering Information**

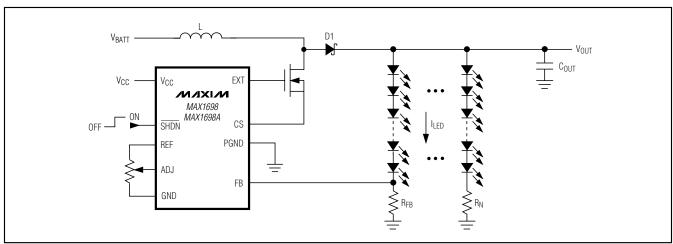
**Features** 

PART	TEMP RANGE	PIN- PACKAGE	PKG CODE
MAX1698EUB	-40°C to +85°C	10μMAX	U10-2
MAX1698AEUB	-40°C to +85°C	10µMAX	U10-2

## Pin Configuration



## Typical Operating Circuit



MIXIM

Maxim Integrated Products 1

### **ABSOLUTE MAXIMUM RATINGS**

Vcc. SHDN to GND0.3V to +6V	Operating Temperature Range40°C to +85°C
EXT, FB, CS, ADJ, REF to GND0.3V to (V <sub>CC</sub> + 0.3V)	Junction Temperature+150°C
GND to PGND±0.3V	Storage Temperature Range65°C to +150°C
Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )	Lead Temperature Range (soldering, 10s)+300°C
10-Pin $\mu$ MAX (derate 5.6mW/°C above $\pm$ 70°C) 444mW	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = +3.3V, T_A = 0^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$ 

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Supply Voltage	Vcc			2.7		5.5	V
Quiescent Supply Current	Icc	$V_{FB} = 0.3V$			260	500	μΑ
Undervoltage Lockout		Rising edge		2.25	2.4	2.55	V
Undervoltage Hysteresis					80		mV
FB Regulation Voltage	V <sub>FB</sub>	ADJ = REF		285	300	315	mV
To Regulation Voltage	VFB	$V_{ADJ} = 100 \text{mV}$	V <sub>ADJ</sub> = 100mV		24	30	IIIV
CS Trip Current		FB = GND	MAX1698A	2.0	2.4	2.8	A
OS INP Current		TB = GND	MAX1698	0.8	1.5	2.5	
CS Input Current	I <sub>CS</sub>					0.8	A <sub>RMS</sub>
Minimum Off Time	toff(MIN)	FB = GND, ADJ = F	FB = GND, ADJ = REF		1.0	1.2	μs
Maximum On Time	ton(max)	FB = GND, ADJ = REF, CS = GND		10	15	20	μs
ADJ Start Threshold				30	50	70	mV
ADJ Input Range	V <sub>ADJ</sub>			0.03		REF	V
FB Input Bias Current	I <sub>FB</sub>	V <sub>FB</sub> = 300mV		-15		15	nA
ADJ Input Bias Current	I <sub>ADJ</sub>	ADJ = REF		-50		50	nA
Shutdown Supply Current		SHDN = GND			0.01	1	μΑ
REF Output Voltage	V <sub>REF</sub>	I <sub>REF</sub> = 0		1.20	1.25	1.30	V
REF Load Regulation	ΔV <sub>REF</sub>	$I_{REF} = 0$ to 150 $\mu$ A			-2	-25	mV
REF Short-Circuit Current		REF = GND			0.45	1	mA
REF Power-Supply Rejection Ratio	PSRR	$V_{CC} = 2.7V \text{ to } 5.5V$			+0.3	+2	mV/V
EXT Driver Sink/Source Current		V <sub>CC</sub> = 5V, EXT = 2V	1		0.2		А
EXT Driver On-Resistance		V <sub>CC</sub> = 5V				8	Ω
SHDN Input High Voltage	VIH	$V_{CC} = 2.7V \text{ to } 5.5V$		2			V
SHDN Input Low Voltage	VIL	V <sub>CC</sub> = 2.7V to 5.5V				0.8	V
SHDN Input Bias Current	ISHDN	V <sub>CC</sub> = 2.7V to 5.5V		-1		1	μΑ

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#### **ELECTRICAL CHARACTERISTICS**

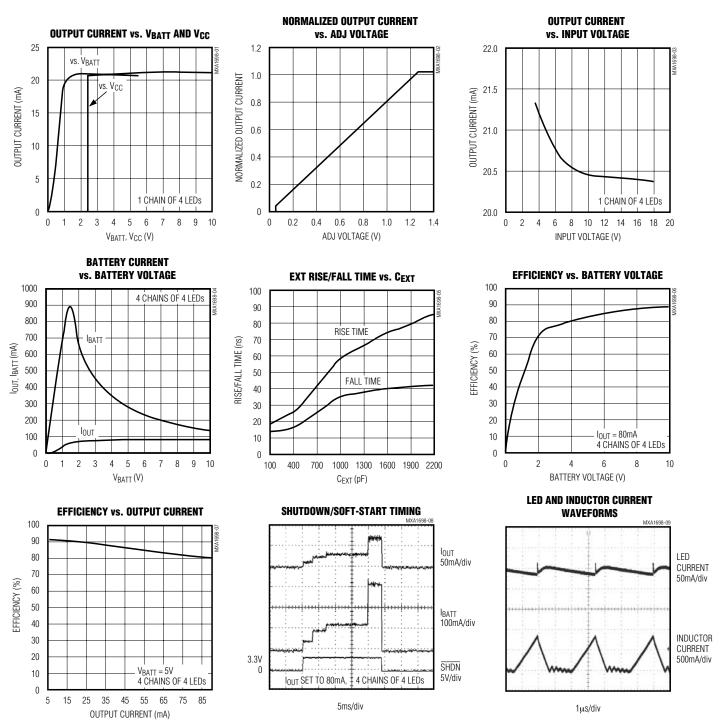
 $(V_{CC} = +3.3V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted.}) \text{ (Note 1)}$ 

PARAMETER	SYMBOL	CONDITIONS		MIN	MAX	UNITS
Supply Voltage	V <sub>CC</sub>			2.7	5.5	V
Quiescent Supply Current	ICC	$V_{FB} = 0.3V$			500	μΑ
Undervoltage Lockout		Rising edge		2.20	2.65	V
FB Regulation Voltage	V <sub>FB</sub>	ADJ = REF	ADJ = REF		320	mV
The Hegulation Voltage	A FB	V <sub>ADJ</sub> = 100mV		13	35	IIIV
CS Trip Current		FB = GND	MAX1698A	2.0	3.0	A
CS Trip Current			MAX1698	0.8	3.0	
Minimum Off Time	toff(MIN)	FB = GND, ADJ = REF	FB = GND, ADJ = REF		1.4	μs
Maximum On Time	ton(max)	FB = GND, ADJ = REF	FB = GND, ADJ = REF, CS = GND		21	μs
ADJ Start Threshold				25	75	mV
FB Input Bias Current	I <sub>FB</sub>	V <sub>FB</sub> = 300mV	V <sub>FB</sub> = 300mV		20	nA
ADJ Input Bias Current	I <sub>ADJ</sub>	ADJ = REF		-50	50	nA
Shutdown Supply Current		SHDN = GND			1	μΑ
REF Output Voltage	V <sub>REF</sub>	I <sub>REF</sub> = 0		1.17	1.33	V
REF Load Regulation	$\Delta V_{REF}$	$I_{REF} = 0$ to 150 $\mu$ A			-30	mV
REF Short-Circuit Current		REF = GND			1	mA
REF Power-Supply Rejection Ratio	PSRR	V <sub>CC</sub> = 2.7V to 5.5V			+2	mV/V
EXT On-Resistance		V <sub>CC</sub> = 5V			8	Ω
SHDN Input High Voltage	VIH	V <sub>CC</sub> = 2.7V to 5.5V		2		V
SHDN Input Low Voltage	V <sub>IL</sub>	V <sub>CC</sub> = 2.7V to 5.5V			0.8	V
SHDN Input Bias Current	ISHDN	V <sub>CC</sub> = 2.7V to 5.5V		-1	1	μΑ

Note 1: Specifications to -40°C are guaranteed by design, not production tested.

## Typical Operating Characteristics

(Circuit of Figure 2, VCC = VBATT = 3.3V, VADJ = VREF, TA = +25°C, unless otherwise noted.)



## **Pin Description**

PIN	NAME	FUNCTION			
1	V <sub>CC</sub>	IC Supply Voltage Input. Power for internal circuitry. Input range is 2.7V to 5.5V.			
2	SHDN	Active-Low Shutdown Input. In shutdown, the MOSFET turns off, but a current path still exists between the input and output. The minimum forward voltage of the LED array must exceed the maximum VBATT to ensure that the LEDs are off in shutdown.			
3	REF	1.25V Reference Output. Capable of sourcing 150µA for external loads. This pin is internally compensated. Do not connect any bypass capacitors at REF.			
4	ADJ	Adjust Input. Allows dynamic adjustment of the output current. FB regulates to 300mV when ADJ = REF.			
5, 7	GND	Ground			
6	FB	Feedback Input. Connect to the external LED current-sense feedback resistor.			
8	PGND	Power Ground			
9	CS	FET Current-Sense Input			
10	EXT	Gate Driver Output			

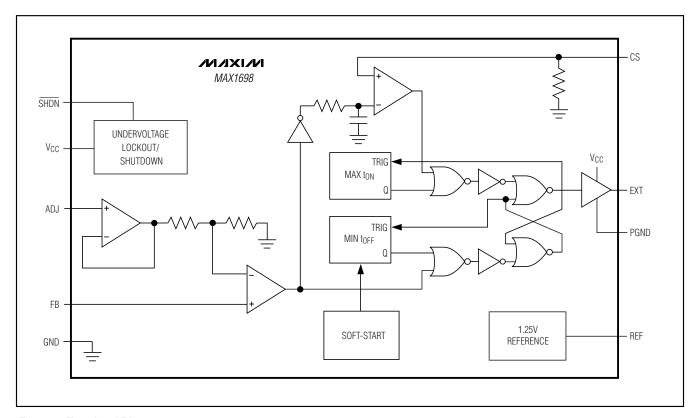


Figure 1. Functional Diagram

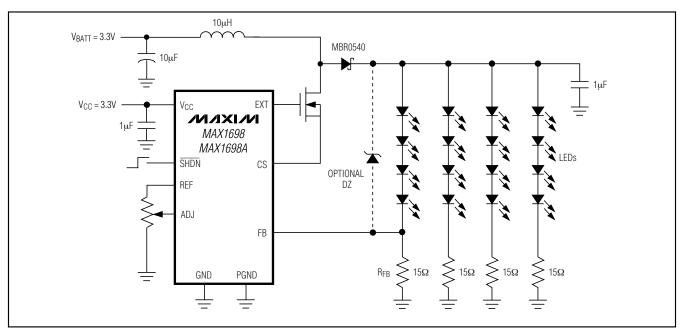


Figure 2. Typical Operating Circuit

## **Detailed Description**

The MAX1698/MAX1698As' high efficiency and small size make them ideally suited to drive LEDs. They operate as a boost DC-DC converter that controls output current rather than voltage. Losses are minimized by a low, 300mV current-sense threshold. In the standard configuration, a feedback resistor, RFB, sets the current through the primary chain of LEDs. Additional chains of matching LEDs can be added with an equivalent resistor. In matched LED arrays, the secondary chain currents closely track the primary chain. An optional zener diode, D2, prevents overvoltage in the event that one of the LEDs in the primary chain becomes an open circuit. The LED brightness can be adjusted dynamically by a voltage input at ADJ.

#### Shutdown

In shutdown, the supply current is reduced below 1µA. EXT goes low in shutdown, shutting off the external N-channel FET. This leaves a current path between the input and the LEDs through the boost inductor and catch diode. The minimum forward voltage of the LED array must exceed the maximum VBATT to ensure that the LEDs remain off in shutdown. Typical shutdown timing characteristics are shown in the *Typical Operating Characteristics*.

#### Soft-Start

The MAX1698/MAX1698A include a soft-start function that eliminates input current surges at turn-on. They do this by extending the external FET driver (EXT) minimum off-time during start-up. During the first 512 switching cycles, the minimum off-time is 5 $\mu$ s. It is then allowed to drop to 2 $\mu$ s for the next 1500 switching cycles. After that time, the minimum off-time falls to the 1 $\mu$ s value used during normal operation. (See Shutdown/Soft-Start Timing in the *Typical Operating Characteristics* section.)

## **Design Procedure**

#### **Setting the Maximum LED Current**

Resistor RFB sets the maximum current in the primary chain of LEDs:

$$R_{FB} = \frac{300mV}{I_{LEDMAX}}$$

where ILEDMAX is the maximum LED current.

#### **Adjusting LED Current**

RFB sets the maximum LED current. This current can be reduced proportional to the voltage at the ADJ pin (see Normalized Output Current vs. ADJ Voltage in the *Typical Operating Characteristics* section). Figure 3

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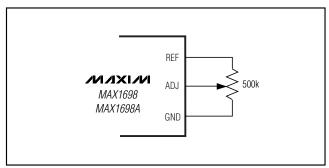


Figure 3. Adjusting LED Current

shows the standard method of setting the ADJ voltage. Use the following equation to determine ILED:

$$I_{LED} = \frac{V_{ADJ}}{4.16 \cdot R_{FB}}$$

where V<sub>ADJ</sub> is the voltage at ADJ. Note that ADJ voltages below 50mV turn the LEDs off.

#### **Inductor Selection**

Choose an inductor with low DC resistance (in the neighborhood of  $100m\Omega$ ) to minimize losses. A typical inductance value for L is  $10\mu H$ ; however, values from  $3.3\mu H$  to  $100\mu H$  can also be used. Higher inductor values reduce the MAX1698's switching frequency. The typical operating frequency is given by:

$$f = \frac{0.67 \cdot V_{BATT}}{I}$$

The MAX1698/MAX1698A limit peak inductor current to 1.5A, but also contains a control loop that reduces inductor current as a function of output power. For a given output power, the required inductor peak current rating is approximately set by:

$$IL(PEAK) = 1.0 \cdot POUT$$

where  $P_{OUT}$  is the output power to all LED banks in watts and  $I_{L(PEAK)}$  is in amperes.

#### **Capacitor Selection**

The exact value of output capacitance is not critical. Typical values for the output capacitor are  $0.1\mu F$  to  $10\mu F$ . Larger values help reduce output ripple at the expense of size and higher cost.

The requirements of the input capacitor depend on the type of the input voltage source. However, in many applications, the same capacitor type and value are used for both the input and output capacitors.

#### **Transistor Selection**

The MAX1698/MAX1698A drive an external N-channel MOSFET. Since the gate drive voltage is derived from VCC, best performance is achieved with low-threshold NFETs that specify on-resistance with gate-source voltages (VGS) at the voltage supplied at VCC or less. For best results, minimize the FET's RDS(ON). The external NFET's maximum drain-to-source voltage (VDS(MAX)) must exceed the output voltage.

#### Catch Diode (D1) Selection

The MAX1698/MAX1698As' high-switching frequency demands a high-speed rectifier. Schottky diodes are recommended for most applications, due to their fast recovery time and low forward-voltage drop. Ensure that the diode's average and peak current ratings exceed the average output current and peak inductor current, respectively. In addition, the diode's reverse breakdown voltage must exceed V<sub>OUT</sub>. For output voltages exceeding 40V, high-speed silicon rectifiers may be required for their higher breakdown voltages.

#### **Zener Diode**

For applications requiring open-circuit protection if one of the LEDs in the primary chain opens, add a zener diode as shown in Figure 2. The zener diode protects the MOSFET and output capacitor if the current feedback signal is lost. The zener voltage should exceed the maximum forward voltage of the LED network by at least 2V.

## \_Applications Information

#### **PCB Layout**

Due to fast switching waveforms and high-current paths, careful PCB layout is required. Protoboards and wire-wrap boards should not be used for evaluation. An EV kit (MAX1698EVKIT) is available to aid most designs.

When laying out a board, minimize trace lengths to CS, the inductor, diode, input capacitor, and output capacitor. Keep traces short, direct, and wide. Keep noisy traces, such as the inductor's traces, away from FB. VCC's bypass capacitor should be placed as close to the IC as possible.

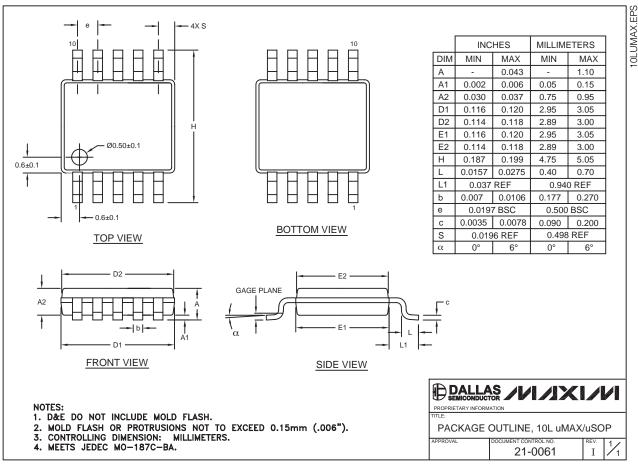
Refer to the MAX1698 EV kit for an example of proper layout.

\_Chip Information

TRANSISTOR COUNT: 2180

### **Package Information**

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



Note: The MAX1698 does not have an exposed pad.

\_Revision History

Pages changed at Rev 2: 1, 2, 8

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